

# XPort6196

Small Form Factor (SFF) 2 TB Removable SATA Solid-State Drive (SSD)

- ▶ Small Form Factor (SFF) utilizing a fully tested and qualified, high-reliability, 2.5 in. rugged SSD
- ▶ -40°C to 85°C operating temperature range
- ▶ High-reliability rugged connector
- ▶ Hot Swap capabilities possible in some configurations
- ▶ Easy insertion and extraction mechanism
- ▶ Designed for rugged environments
- ▶ Provides up to 2 TB of NAND flash
- ▶ Based on MLC NAND flash technology
- ▶ Global wear-leveling support for added memory endurance
- ▶ ATA Secure Erase support
- ▶ Military sanitization support



## XPort6196

The XPort6196 is the ideal solution for today's ruggedized secure storage requirements. The XPort6196 utilizes a fully tested and qualified, high-reliability 2.5 in. Solid-State Drive (SSD). The XPort6196 is capable of operating within the demanding environments of MIL-STD-810F, including harsh temperatures from -40°C to 85°C, as well as rigorous shock and vibration conditions.

Designed with a high-reliability connector, the XPort6196 will support thousands of insertions and extractions. To meet high density requirements, the XPort6196 supports configurations with up to 2 TB of NAND flash.

# X-ES

Extreme Engineering Solutions

*...Always Fast*

## Extreme Engineering Solutions

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**Physical Characteristics**

- Small Form Factor (SFF) incorporating a standard 2.5 in. SSD module
- Without rails: 100.18 mm (L) x 69.97 mm (W) x 9.45 mm (H)
- With rails: 112.87 mm (L) x 80.62 mm (W) x 9.45 mm (H)
- Development and deployable carrier systems available

**Storage Characteristics**

- One SATA port capable of 6 Gb/s
- MLC technology
- Up to 2 TB of NAND flash

**Endurance**

- High-reliability rugged connector
- Global wear-leveling, bad block management, and drive over-provisioning

**Security**

- ATA Secure Erase support
- Military sanitization support

**Environmental Requirements**

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 5

**Power Requirements**

- Max power dissipation is dependent on drive configuration. Contact X-ES for details.

<b>Ruggedization Level</b>	<b>Level 5</b>
<b>Cooling Method</b>	Conduction-Cooled
<b>Operating Temperature</b>	-40 to +85°C (board rail surface)
<b>Storage Temperature</b>	-55 to +105°C (maximum)
<b>Vibration</b>	0.1 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz
<b>Shock</b>	40 g, 11 ms sawtooth
<b>Humidity</b>	0% to 95% non-condensing

† Contact factory for airflow rate details.

**XPort6196 Pictured with XPand6200**

